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Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

2014.10	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	2
Number of Macrocells	32
Number of Gates	600
Number of I/O	36
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7032lc44-10

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MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and highspeed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)— and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.

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For more information on development tools, see the MAX+PLUS II Programmable Logic Development System & Software Data Sheet and the Quartus Programmable Logic Development System & Software Data Sheet.

Functional Description

The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.

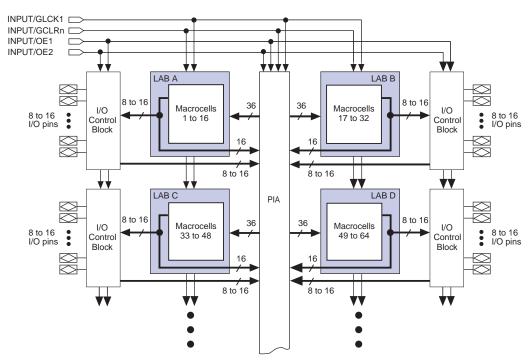
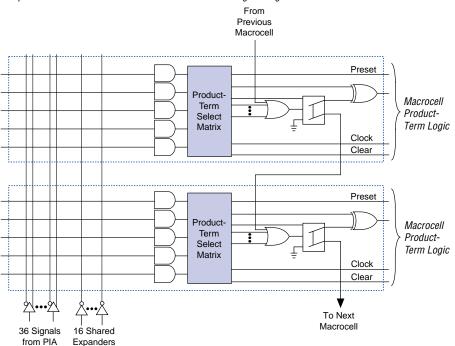


Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram

The compiler can allocate up to three sets of up to five parallel expanders automatically to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay (t_{PEXP}). For example, if a macrocell requires 14 product terms, the Compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms and the second set includes four product terms, increasing the total delay by $2 \times t_{PEXP}$.

Two groups of 8 macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lowernumbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of 8, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them. Figure 6 shows how parallel expanders can be borrowed from a neighboring macrocell.

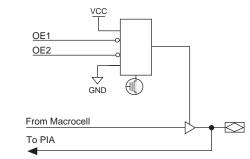
Figure 6. Parallel Expanders



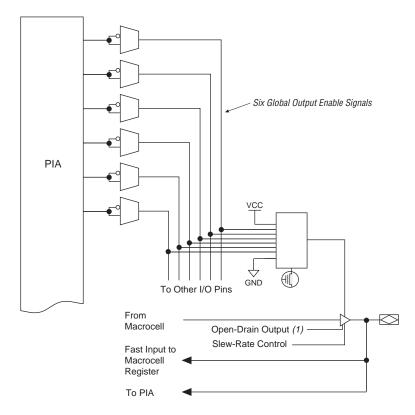
Unused product terms in a macrocell can be allocated to a neighboring macrocell.

Figure 8. I/O Control Block of MAX 7000 Devices

EPM7032, EPM7064 & EPM7096 Devices







Note:

(1) The open-drain output option is available only in MAX 7000S devices.

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000S Device

The time required to program a single MAX 7000S device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$
where: t_{PROG} = Programming time
 t_{PPULSE} = Sum of the fixed times to erase, program, and
verify the EEPROM cells
 $Cycle_{PTCK}$ = Number of TCK cycles to program a device
 f_{TCK} = TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000S device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$
where: t_{VER} = Verify time
 t_{VPULSE} = Sum of the fixed times to verify the EEPROM cells
 $Cycle_{VTCK}$ = Number of TCK cycles to verify a device

Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (i.e., with the Turbo BitTM option turned on) or low-power (i.e., with the Turbo Bit option turned off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder (t_{LPA}) for the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , and t_{SEXP} , \mathbf{t}_{ACL} , and \mathbf{t}_{CPPW} parameters.

Output Configuration

MAX 7000 device outputs can be programmed to meet a variety of system-level requirements.

MultiVolt I/O Interface

MAX 7000 devices—except 44-pin devices—support the MultiVolt I/O interface feature, which allows MAX 7000 devices to interface with systems that have differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCINT pins must always be connected to a 5.0-V power supply. With a 5.0-V V_{CCINT} level, input voltage thresholds are at TTL levels, and are therefore compatible with both 3.3-V and 5.0-V inputs.

The VCCIO pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems. When V_{CCIO} is connected to a 3.3-V supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V_{CCIO} levels lower than 4.75 V incur a nominally greater timing delay of t_{OD2} instead of t_{OD1} .

Open-Drain Output Option (MAX 7000S Devices Only)

MAX 7000S devices provide an optional open-drain (functionally equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

devices.

Figure 9 shows the timing requirements for the JTAG signals.

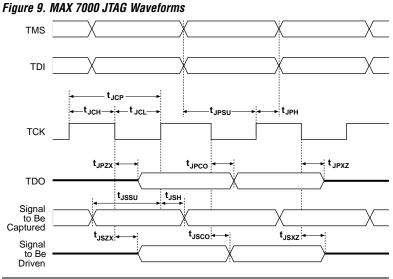


Table 12 shows the JTAG timing parameters and values for MAX 7000S

Table 1	2. JTAG Timing Parameters & Values for MAX 70	00S De	vices	
Symbol	Parameter	Min	Мах	Unit
t _{JCP}	TCK clock period	100		ns
t _{JCH}	TCK clock high time	50		ns
t _{JCL}	TCK clock low time	50		ns
t _{JPSU}	JTAG port setup time	20		ns
t _{JPH}	JTAG port hold time	45		ns
t _{JPCO}	JTAG port clock to output		25	ns
t _{JPZX}	JTAG port high impedance to valid output		25	ns
t _{JPXZ}	JTAG port valid output to high impedance		25	ns
t _{JSSU}	Capture register setup time	20		ns
t _{JSH}	Capture register hold time	45		ns
t _{JSCO}	Update register clock to output		25	ns
t _{JSZX}	Update register high impedance to valid output		25	ns
t _{JSXZ}	Update register valid output to high impedance		25	ns



For more information, see *Application Note* 39 (IEEE 1149.1 (JTAG) *Boundary-Scan Testing in Altera Devices*).

Table 1	5. MAX 7000 5.0-V Device DC (Operating Conditions Note (9)			
Symbol	Parameter	Conditions	Min	Max	Unit
V _{IH}	High-level input voltage		2.0	V _{CCINT} + 0.5	V
V _{IL}	Low-level input voltage		-0.5 (8)	0.8	V
V _{OH}	5.0-V high-level TTL output voltage	$I_{OH} = -4 \text{ mA DC}, V_{CCIO} = 4.75 \text{ V} (10)$	2.4		V
	3.3-V high-level TTL output voltage	$I_{OH} = -4 \text{ mA DC}, V_{CCIO} = 3.00 \text{ V} (10)$	2.4		V
	3.3-V high-level CMOS output voltage	I_{OH} = -0.1 mA DC, V_{CCIO} = 3.0 V (10)	V _{CCIO} – 0.2		V
V _{OL}	5.0-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 4.75 V (11)		0.45	V
	3.3-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 3.00 V (11)		0.45	V
	3.3-V low-level CMOS output voltage	I _{OL} = 0.1 mA DC, V _{CCIO} = 3.0 V(11)		0.2	V
I _I	Leakage current of dedicated input pins	$V_{I} = -0.5$ to 5.5 V (11)	-10	10	μΑ
I _{OZ}	I/O pin tri-state output off-state current	V _I = -0.5 to 5.5 V (11), (12)	-40	40	μA

Table 1	Table 16. MAX 7000 5.0-V Device Capacitance: EPM7032, EPM7064 & EPM7096 Devices Note (13)									
Symbol	Parameter	Conditions	Min	Max	Unit					
CIN	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		12	pF					
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		12	pF					

Table 1	Table 17. MAX 7000 5.0-V Device Capacitance: MAX 7000E Devices Note (13)								
Symbol	Parameter	Conditions	Min	Max	Unit				
C _{IN}	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		15	pF				
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		15	pF				

Table 1	Table 18. MAX 7000 5.0-V Device Capacitance: MAX 7000S Devices Note (13)									
Symbol	Parameter	Conditions	Min	Max	Unit					
CIN	Dedicated input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		10	pF					
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		10	pF					

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Tables 19 through 26 show the MAX 7000 and MAX 7000E AC $\,$ operating conditions.

Symbol	Parameter	Conditions	-6 Speed Grade		-7 Spee	d Grade	Unit
			Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t _{SU}	Global clock setup time		5.0		6.0		ns
t _H	Global clock hold time		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input	(2)	2.5		3.0		ns
t _{FH}	Global clock hold time of fast input	(2)	0.5		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5	ns
t _{CH}	Global clock high time		2.5		3.0		ns
t _{CL}	Global clock low time		2.5		3.0		ns
t _{ASU}	Array clock setup time		2.5		3.0		ns
t _{AH}	Array clock hold time		2.0		2.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5	ns
t _{ACH}	Array clock high time		3.0		3.0		ns
t _{ACL}	Array clock low time		3.0		3.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	3.0		3.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.6		8.0	ns
^f сnт	Maximum internal global clock frequency	(5)	151.5		125.0		MHz
t _{ACNT}	Minimum array clock period			6.6		8.0	ns
facnt	Maximum internal array clock frequency	(5)	151.5		125.0		MHz
f _{MAX}	Maximum clock frequency	(6)	200		166.7		MHz

Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	0E (-10P)		00 (-10) Doe (-10)	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.5		1.0	ns
t _{IO}	I/O input pad and buffer delay			0.5		1.0	ns
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns
t _{SEXP}	Shared expander delay			5.0		5.0	ns
t _{PEXP}	Parallel expander delay			0.8		0.8	ns
t _{LAD}	Logic array delay			5.0		5.0	ns
t _{LAC}	Logic control array delay			5.0		5.0	ns
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		1.5		2.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		2.0		2.5	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		5.5		6.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		5.0		5.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		5.5		5.5	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns
t _{SU}	Register setup time		2.0		3.0		ns
t _H	Register hold time		3.0		3.0		ns
t _{FSU}	Register setup time of fast input	(2)	3.0		3.0		ns
t _{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t _{RD}	Register delay			2.0		1.0	ns
t _{COMB}	Combinatorial delay			2.0		1.0	ns
t _{IC}	Array clock delay			5.0		5.0	ns
t _{EN}	Register enable time			5.0		5.0	ns
t _{GLOB}	Global control delay			1.0		1.0	ns
t _{PRE}	Register preset time			3.0		3.0	ns
t _{CLR}	Register clear time			3.0		3.0	ns
t _{PIA}	PIA delay			1.0		1.0	ns
t _{LPA}	Low-power adder	(8)		11.0		11.0	ns

Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	OE (-12P)		00 (-12) DOE (-12)	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			1.0		2.0	ns
t _{IO}	I/O input pad and buffer delay			1.0		2.0	ns
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns
t _{SEXP}	Shared expander delay			7.0		7.0	ns
t _{PEXP}	Parallel expander delay			1.0		1.0	ns
t _{LAD}	Logic array delay			7.0		5.0	ns
t _{LAC}	Logic control array delay			5.0		5.0	ns
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 5.0 V$	C1 = 35 pF		1.0		3.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		4.0	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.0		7.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 5.0 V$	C1 = 35 pF		6.0		6.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		7.0		7.0	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		10.0		10.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0	ns
t _{SU}	Register setup time		1.0		4.0		ns
t _H	Register hold time		6.0		4.0		ns
t _{FSU}	Register setup time of fast input	(2)	4.0		2.0		ns
t _{FH}	Register hold time of fast input	(2)	0.0		2.0		ns
t _{RD}	Register delay			2.0		1.0	ns
t _{COMB}	Combinatorial delay			2.0		1.0	ns
t _{IC}	Array clock delay			5.0		5.0	ns
t _{EN}	Register enable time			7.0		5.0	ns
t _{GLOB}	Global control delay			2.0		0.0	ns
t _{PRE}	Register preset time			4.0		3.0	ns
t _{CLR}	Register clear time			4.0		3.0	ns
t _{PIA}	PIA delay			1.0		1.0	ns
t _{LPA}	Low-power adder	(8)		12.0		12.0	ns

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	15	-1	5T	-2	20	
			Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			2.0		2.0		3.0	ns
t _{IO}	I/O input pad and buffer delay			2.0		2.0		3.0	ns
t _{FIN}	Fast input delay	(2)		2.0		-		4.0	ns
t _{SEXP}	Shared expander delay			8.0		10.0		9.0	ns
t _{PEXP}	Parallel expander delay			1.0		1.0		2.0	ns
t _{LAD}	Logic array delay			6.0		6.0		8.0	ns
tLAC	Logic control array delay			6.0		6.0		8.0	ns
t _{IOE}	Internal output enable delay	(2)		3.0		-		4.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		4.0		4.0		5.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		5.0		-		6.0	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		8.0		-		9.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		6.0		6.0		10.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		7.0		-		11.0	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		10.0		-		14.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0		10.0	ns
t _{SU}	Register setup time		4.0		4.0		4.0		ns
t _H	Register hold time		4.0		4.0		5.0		ns
t _{FSU}	Register setup time of fast input	(2)	2.0		-		4.0		ns
t _{FH}	Register hold time of fast input	(2)	2.0		-		3.0		ns
t _{RD}	Register delay			1.0		1.0		1.0	ns
t _{COMB}	Combinatorial delay			1.0		1.0		1.0	ns
t _{IC}	Array clock delay			6.0		6.0		8.0	ns
t _{EN}	Register enable time			6.0		6.0		8.0	ns
t _{GLOB}	Global control delay			1.0		1.0		3.0	ns
t _{PRE}	Register preset time			4.0		4.0		4.0	ns
t _{CLR}	Register clear time			4.0		4.0		4.0	ns
t _{PIA}	PIA delay			2.0		2.0		3.0	ns
t _{LPA}	Low-power adder	(8)		13.0		15.0		15.0	ns

Table 27. EPM7032S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions				Speed	Grade				Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
f _{ACNT}	Maximum internal array clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
f _{MAX}	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	5	-6		-7		-*	10	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t _{IO}	I/O input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t _{FIN}	Fast input delay			2.2		2.1		2.5		1.0	ns
t _{SEXP}	Shared expander delay			3.1		3.8		4.6		5.0	ns
t _{PEXP}	Parallel expander delay			0.9		1.1		1.4		0.8	ns
t _{LAD}	Logic array delay			2.6		3.3		4.0		5.0	ns
t _{LAC}	Logic control array delay			2.5		3.3		4.0		5.0	ns
t _{IOE}	Internal output enable delay			0.7		0.8		1.0		2.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		0.4		1.5	ns
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		0.9		2.0	ns
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		5.4		5.5	ns
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t _{SU}	Register setup time		0.8		1.0		1.3		2.0		ns
t _H	Register hold time		1.7		2.0		2.5		3.0		ns
t _{FSU}	Register setup time of fast input		1.9		1.8		1.7		3.0		ns
t _{FH}	Register hold time of fast input		0.6		0.7		0.8		0.5		ns
t _{RD}	Register delay			1.2		1.6		1.9		2.0	ns
t _{COMB}	Combinatorial delay			0.9		1.1		1.4		2.0	ns
t _{IC}	Array clock delay			2.7		3.4		4.2		5.0	ns
t _{EN}	Register enable time			2.6		3.3		4.0		5.0	ns
t _{GLOB}	Global control delay			1.6		1.4		1.7		1.0	ns
t _{PRE}	Register preset time			2.0		2.4		3.0		3.0	ns
t _{CLR}	Register clear time			2.0		2.4		3.0		3.0	ns

Table 33. EPM7160S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions				Speed	Grade)			Unit
			-6 -		7	-10		-15			
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACNT}	Minimum array clock period			6.7		8.2		10.0		13.0	ns
f _{acnt}	Maximum internal array clock frequency	(4)	149.3		122.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

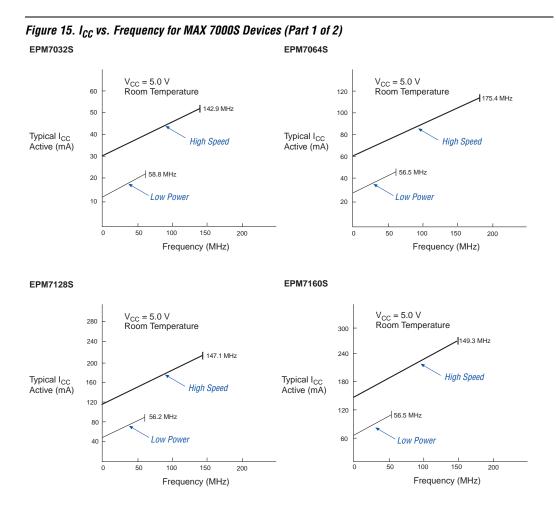
Symbol	Parameter	Conditions				Speed	Grade									
			-6		-7		-10		-15							
			Min	Max	Min	Max	Min	Max	Min	Max						
t _{IN}	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns					
t _{IO}	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns					
t _{FIN}	Fast input delay			2.6		3.2		1.0		2.0	ns					
t _{SEXP}	Shared expander delay			3.6		4.3		5.0		8.0	ns					
t _{PEXP}	Parallel expander delay			1.0		1.3		0.8		1.0	ns					
t _{LAD}	Logic array delay			2.8		3.4		5.0		6.0	ns					
t _{LAC}	Logic control array delay			2.8		3.4		5.0		6.0	ns					
t _{IOE}	Internal output enable delay			0.7		0.9		2.0		3.0	ns					
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns					
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.9		1.0		2.0		5.0	ns					
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns					
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns					
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns					
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns					
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns					
t _{SU}	Register setup time		1.0		1.2		2.0		4.0		ns					
t _H	Register hold time		1.6		2.0		3.0		4.0		ns					
t _{FSU}	Register setup time of fast input		1.9		2.2		3.0		2.0		ns					
t _{FH}	Register hold time of fast input		0.6		0.8		0.5		1.0		ns					
t _{RD}	Register delay			1.3		1.6		2.0		1.0	ns					
t _{COMB}	Combinatorial delay			1.0		1.3		2.0		1.0	ns					
t _{IC}	Array clock delay			2.9		3.5		5.0		6.0	ns					
t _{EN}	Register enable time			2.8		3.4		5.0		6.0	ns					
t _{GLOB}	Global control delay			2.0		2.4		1.0		1.0	ns					
t _{PRE}	Register preset time			2.4		3.0		3.0		4.0	ns					

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Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	7	-1	10	-1	5	
			Min	Max	Min	Max	Min	Max	-
t _{IN}	Input pad and buffer delay			0.3		0.5		2.0	ns
t _{IO}	I/O input pad and buffer delay			0.3		0.5		2.0	ns
t _{FIN}	Fast input delay			3.4		1.0		2.0	ns
t _{SEXP}	Shared expander delay			3.9		5.0		8.0	ns
t _{PEXP}	Parallel expander delay			1.1		0.8		1.0	ns
t _{LAD}	Logic array delay			2.6		5.0		6.0	ns
t _{LAC}	Logic control array delay			2.6		5.0		6.0	ns
t _{IOE}	Internal output enable delay			0.8		2.0		3.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		8.0	ns
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns
t _{SU}	Register setup time		1.1		2.0		4.0		ns
t _H	Register hold time		1.6		3.0		4.0		ns
t _{FSU}	Register setup time of fast input		2.4		3.0		2.0		ns
t _{FH}	Register hold time of fast input		0.6		0.5		1.0		ns
t _{RD}	Register delay			1.1		2.0		1.0	ns
t _{COMB}	Combinatorial delay			1.1		2.0		1.0	ns
t _{IC}	Array clock delay			2.9		5.0		6.0	ns
t _{EN}	Register enable time			2.6		5.0		6.0	ns
t _{GLOB}	Global control delay			2.8		1.0		1.0	ns
t _{PRE}	Register preset time			2.7		3.0		4.0	ns
t _{CLR}	Register clear time			2.7		3.0		4.0	ns
t _{PIA}	PIA delay	(7)		3.0		1.0		2.0	ns
t _{LPA}	Low-power adder	(8)		10.0		11.0		13.0	ns

Figure 15 shows typical supply current versus frequency for MAX 7000S devices.



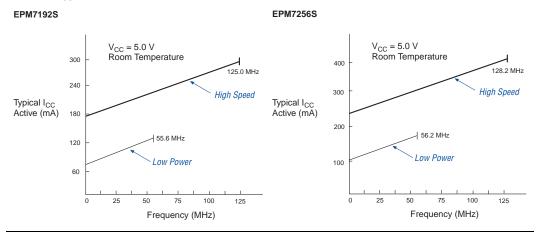


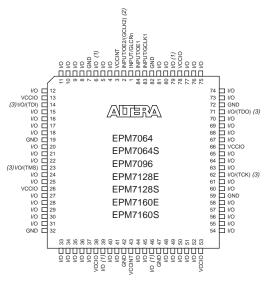
Figure 15. I_{CC} vs. Frequency for MAX 7000S Devices (Part 2 of 2)

Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.

Figure 18. 84-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



84-Pin PLCC

Notes:

- (1) Pins 6, 39, 46, and 79 are no-connect (N.C.) pins on EPM7096, EPM7160E, and EPM7160S devices.
- (2) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (3) JTAG ports are available in MAX 7000S devices only.

Figure 19. 100-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

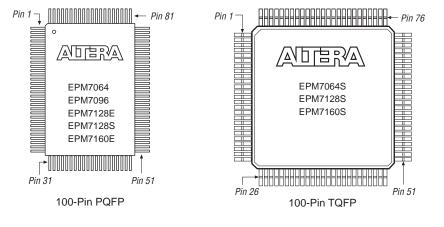


Figure 20. 160-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

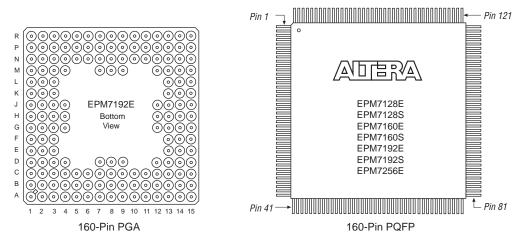


Figure 21. 192-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

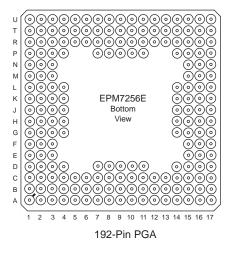


Figure 22. 208-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

